

IN THE CLAIMS

Per the revised amendment practice, a complete listing of all claims in the application follows.

Claims 1-6 (cancelled).

7. (Currently amended) A method of stacking a plurality of die, comprising mounting an upper die on a lower die; and .
defining an angular offset with said mounting, wherein said angular offset allows access to a bonding site on said lower die, and wherein at least one end of said upper die is unsupported.
8. (Previously presented) The method in claim 7, further comprising a step of mounting a lowest die on a substrate.
9. (Previously presented) A method of manufacturing a multichip module including dies, comprising:
stacking said dies in a manner such that corresponding portions of any two of said dies define respective axes, and wherein said axes define an offset angle; and refraining from propping at least one of said dies in a region extending laterally from any underlying die.
10. (Previously presented) A method of manufacturing a multichip module including dies, comprising:
stacking said dies, wherein corresponding portions of any two of said dies define respective axes, and wherein said axes define an offset angle; and allowing at least one end of at least one of said dies to be free of support.
11. (Previously presented) A method of manufacturing a multichip module including dies, comprising:

stacking said dies, wherein corresponding portions of any two of said dies define respective axes, and wherein said axes define an offset angle; and
limiting direct support for a first die of said dies to a region between said first die and a second die of said dies, said second die immediately underlying said first die.

12. (Previously presented) A method of assembling a plurality of dies, comprising:
stacking said plurality of dies along an axis;
establishing an orientation for each die of said plurality of dies;
clearing a line of sight to contact areas of any immediately underlying die
with said orientation for said each die, wherein said line of sight is parallel to said axis;
clearing a line of sight to contact areas of any underlying die with said orientation for said each die; and
directly holding up at least one of said plurality of dies only in a region that intersects said axis.

13. (Previously presented) A method of stacking a plurality of chips
spiraling said plurality of chips around an axis perpendicular to said plurality of chips;
ensuring bond pad clearance to each chip of said plurality of chips; and
limiting reinforcement of at least one of said plurality of chips to regions intersecting said axis.

14. (Previously presented) The method in claim 13, wherein said step of spiraling said plurality of chips around an axis further comprises spiraling said plurality of chips around an axis passing through said each chip.

15. (Previously presented) The method in claim 14, wherein said step of spiraling said plurality of chips around an axis further comprises spiraling said plurality of chips around an axis passing through a center of said each chip.

16. (Previously presented) The method in claim 15, wherein said ensuring step comprises rotating a chip around said axis at least to an extent that a bond pad on an underlying chip is exposed.

17. (Previously presented) A method of arranging dies in a multichip device, comprising:
serially stacking said dies; and
establishing a unique orientation for each die of said dies, wherein said orientation for said each die defines an underlying bond pad clearance, and wherein at least one orientation leaves at least one end of at least one of said dies free of bolstering.